

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

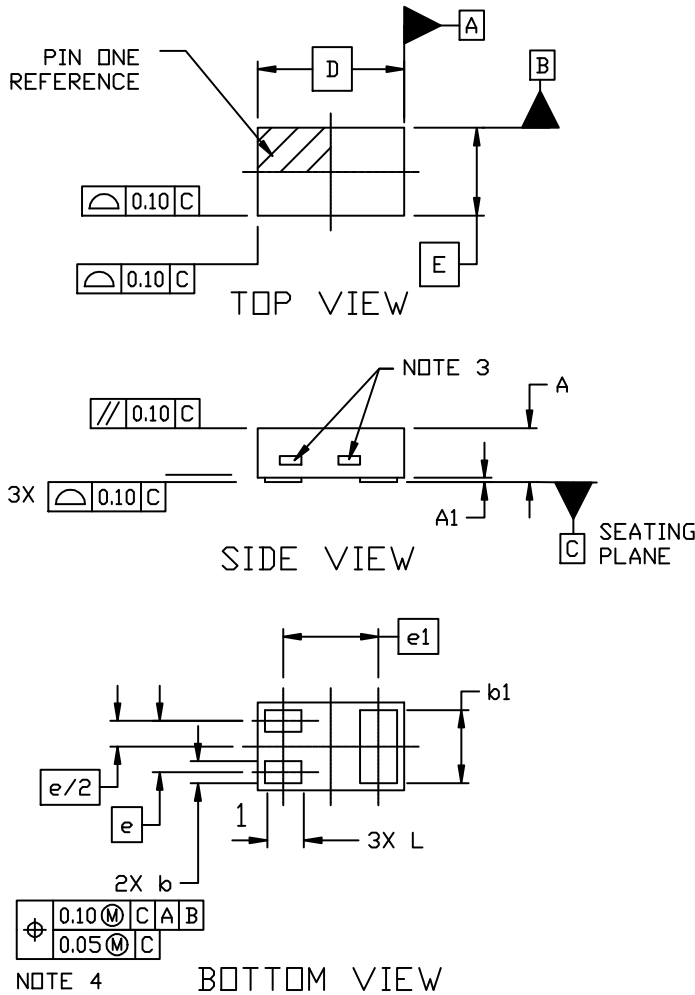
ON Semiconductor®



**X2DFN3 1.0x0.6, 0.35P**  
CASE 714AC  
ISSUE A

DATE 08 JAN 2019

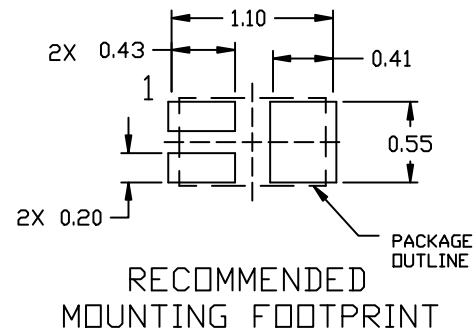
SCALE 8:1



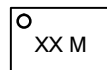
**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. EXPOSED COPPER ALLOWED AS SHOWN.
4. ALL PAD LOCATIONS CONTROLLED WITH THIS POSITIONAL TOLERANCE.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.34	0.37	0.40
A1	0.00	---	0.05
b	0.10	0.15	0.20
b1	0.45	0.50	0.55
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	0.35 BSC		
e1	0.65 BSC		
L	0.20	0.25	0.30



**GENERIC MARKING DIAGRAM\***



XX = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>X2DFN3 1.0x0.6, 0.35P</b>	<b>PAGE 1 OF 1</b>

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